AR1642-EVM-011 Via Fill & Cap Requirements

There are many via-s on the PCB which are either on the pads or close to pads.

These need to filled with non-conductive epoxy to ensure flat surface. In the BGA area they also need to be capped with copper plating.

Near U2 (top assembly):

All the via-s (blind as well as PTH) near the BGA area need to be filled and capped



U2

U1 thermal pad (top assembly):



U4 (top assembly):



U11 (top assembly):



Near U8 and caps around U8 (bottom assembly):



Near U5 (bottom assembly):



Near U9 (bottom assembly)

